

400mW SOD-123 SURFACE MOUNT
Small Outline Gull Wing Lead Plastic Package
Schottky Barrier Diode

Green Product

Absolute Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Units
P_D	Power Dissipation	400	mW
T_{STG}	Storage Temperature Range	-65 to +125	$^\circ\text{C}$
T_J	Operating Junction Temperature	+125	$^\circ\text{C}$
V_{RM}	Repetitive Peak Reverse Voltage SD103AWG	40	V
	SD103BWG	30	V
	SD103CWG	20	V
$I_{F(AV)}$	Average Forward Rectified Current	200	mA

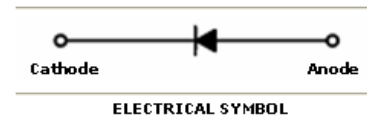
These ratings are limiting values above which the serviceability of the diode may be impaired.



SOD-123 Gull Wing Lead

Specification Features:

- Low Forward Voltage Drop
- Gull Wing Lead SOD-123 Small Outline Plastic Package
- Surface Device Type Mounting
- RoHS Compliant
- Green EMC
- Matte Tin(Sn) Lead Finish
- Band Indicates Cathode
- Weight: approx. 0.01g

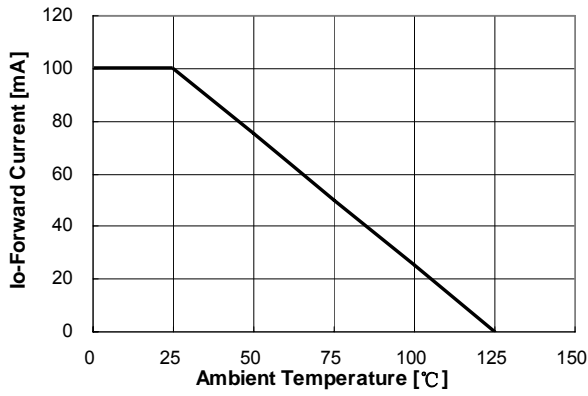
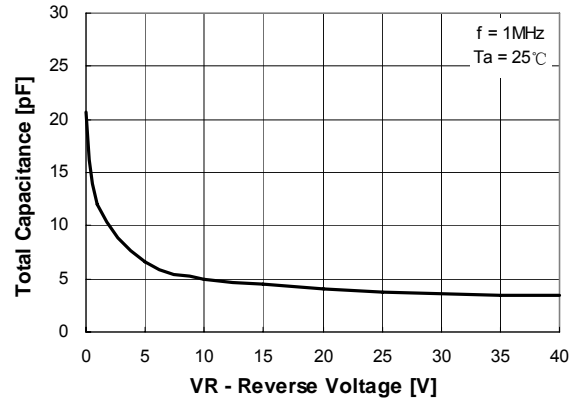
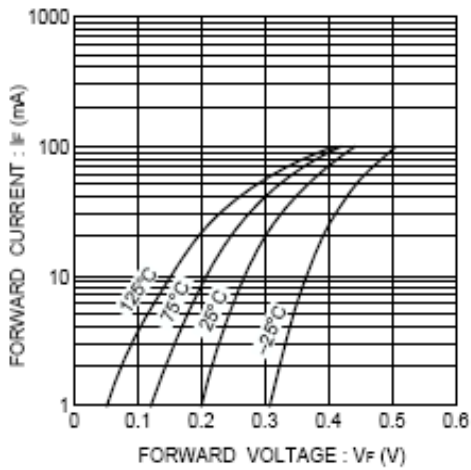
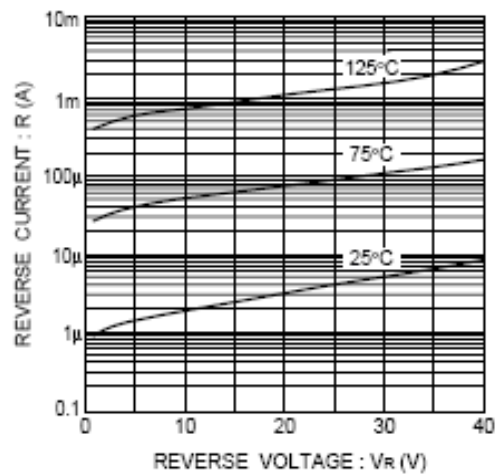


DEVICE MARKING CODES:

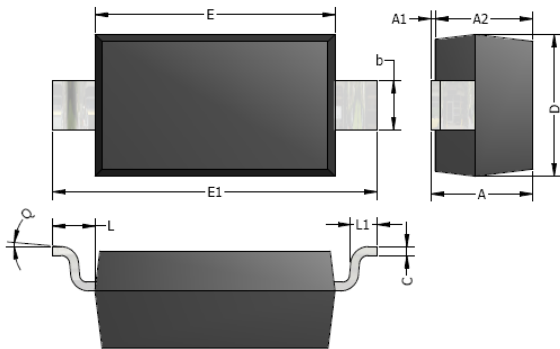
Device Type	Device Marking
SD103AWG	S4
SD103BWG	S5
SD103CWG	S6

Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Condition	Limits			Unit
			Min	Typ	Max	
I_R	Reverse Leakage Current	SD103AWG $V_R=30\text{V}$	---	---	5	μA
		SD103BWG $V_R=20\text{V}$	---	---	5	
		SD103CWG $V_R=10\text{V}$	---	---	5	
V_F	Forward Voltage	$I_F=20\text{mA}$	---	---	0.37	Volts
		$I_F=200\text{mA}$	---	---	0.60	
C_t	Junction Capacitance	$V_R=0\text{V}$ $f=1\text{MHz}$	---	50	---	pF

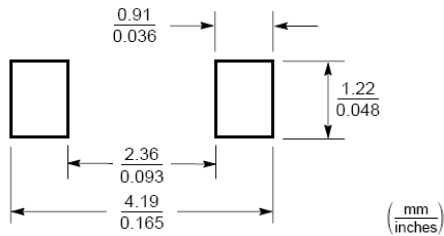
Typical Characteristics

Figure 1. Forward Current Derating Curve

Figure 2. Total Capacitance

Figure 3. Forward Characteristics

Figure 4. Reverse Characteristics

SOD123 Gull Wing Lead Package Outline



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.05	1.25	0.041	0.049
A1	0.00	0.10	0.000	0.004
A2	1.05	1.15	0.041	0.045
b	0.50	0.70	0.020	0.028
c	0.08	0.15	0.003	0.006
D	1.50	1.70	0.059	0.067
E	2.60	2.80	0.102	0.110
E1	3.55	3.85	0.140	0.152
L	0.50 REF.		0.020 REF.	
L1	0.25	0.45	0.010	0.018
θ	0°	8°	0°	8°

Typical Soldering Pattern:



Note:
Dimensions are exclusive of Burrs, Mold Flash & Tie Bar extrusions.

NOTICE

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